

A Pri Inc Inductors (Coils) Detailed Information

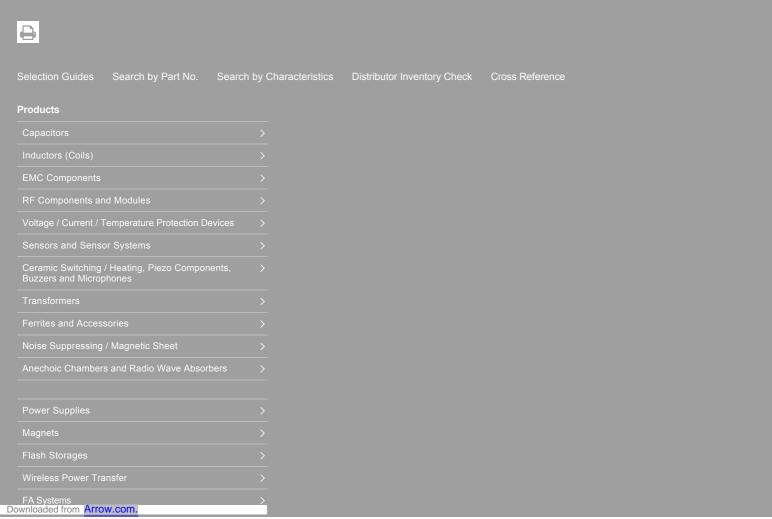
Inductors (Coils)

Product Top Pa		Search by Characteristics	Cross Reference	Catalog	Tech Notes	▼ more
MHQ04	02P8N2HT	000				RoHS REACH Halogen Free Free
Applications	Commercial Grac	le				PDF file of this page
Feature	Non-Mag Core Non-Mag	n-Mag Core Non-Magnetic Core (Dielectric Ceramic)			ener g = . Orangan tene	Contact
Series Type	e MHQ-P			Images are for reference only and show exemplary products.		Documents
001100 1390	Production (Not Recommended for New Design) Recommended Alternate Part No. : <u>MHQ0402PSA8N2HT000</u> (Interc hangeability is not guaranteed.)				Catalog	
Status					Control Real Certificate SVHC/REACH Certificate	
Brand	TDK			-		Product Lineup
Brand						[Selection Guide] Inductors for high frequency
						applications Update
Size						
Length(L)		0.44mm ±0.0	0.44mm ±0.02mm			Technical Support Tools
Width(W)		0.24mm ±0.0	0.24mm ±0.02mm			S-parameter
Thickness Hei	ght	0.24mm ±0.0	0.24mm ±0.02mm			SPICE Netlist (Simple)
Recommended Land Pattern (A)		0.15mm to 0	0.15mm to 0.20mm			Equivalent Circuit Model
Recommended Land Pattern (B)		0.20mm Non	0.20mm Nom.			
Recommended Land Pattern (C)		0.18mm to 0	0.18mm to 0.20mm			
Electrical Char	racteristics					
Inductance		8.2nH ±3% a	8.2nH ±3% at 500MHz			
Rated Current		180mA	180mA			
DC Resistance [Typ.]		690mΩ				
DC Resistance [Max.]		1.2Ω	1.2Ω			
Self Resonant F	Frequency [Min.]	3GHz	3GHz			
Self Resonant Frequency [Typ.]		4.7GHz	4.7GHz			
Q [Min.]		10 at 500MH	10 at 500MHz			
Q [Тур.]		14 at 500MH	14 at 500MHz			
Other						
Operating Temp	. Range (Including Self-Te	emp. Rise) -55 to 125°C				
Soldering Method		Reflow	Reflow			
AEC-Q200 No)			
Packing		Punched (Pa	Punched (Paper)Taping [180mm Reel]			
Package Quant	iity	20000pcs	20000pcs			
Weight		0.00011a	0.00011g			

Characteristic Graph (This is reference data, and does not guarantee the products characteristics.)

Impedance

MHQ0402P8N2HT000	MHQ0402P8N2HT000
Change settings	Change settings
Inductance	Q
MHQ0402P8N2HT000	MHQ0402P8N2HT000
Change settings	Change settings



Transparent Conductive Film	>	
Micro Modules (Substrates with Built-in ICs, Products Utilizing with SESUB)		
Solar Cells		
Biosensor		
Application Specific IC (ASIC) Development and Supply		
Application Guides		
Technical Support		
Tech Library		
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